







This is to certify that

SIGURD MICROELECTRONICS CORPORATION

No. 1, Siwei Road, Hsinchu Industrial Park, Hukou Hsin-Chu Taiwan

with the organizational units/sites as listed in the annex

has implemented and maintains an Electrostatic Discharge Control Program.

Scope:

The production testing of integrated circuits in wafer and package form.

The manufacture of trimmed integrated circuits.

The manufacture of wafer grinding and DPS (Die and Pick place Service).

Through an audit, documented in a report, it was verified that the management system fulfills the requirements of the following standard:

ANSI/ESD S20.20-2021

Certificate registration no. 20002757 ESD-2021

Date of certification 2025-07-08
Valid until 2026-07-18
Lead Auditor Derrick Hsu
ESD Program Manager Arthur Lee

Technical Reviewer Carlton Patterson



DQS Inc.

David Tellez Managing Director







Annex to certificate

Registration no.: 20002757 ESD-2021

SIGURD MICROELECTRONICS CORPORATION

No. 1, Siwei Road, Hsinchu Industrial Park, Hukou Hsin-Chu Taiwan

Location Scope

20002757

SIGURD MICROELECTRONICS CORPORATION The production testing of integrated circuits in

No. 1, Siwei Road, Hsinchu Industrial Park wafer and package form.

Hukou, Hsin-Chu The manufacture of trimmed integrated circuits.

Taiwan

50600370

SIGURD MICROELECTRONICS CORPORATION The production testing of integrated circuits in

No. 11 LANE 169, SEC. 2 wafer and package form.

CHUNG-SHING RD., CHU-TUNG The manufacture of trimmed integrated circuits.

HSIN-CHU The manufacture of wafer grinding and DPS (Die

TAIWAN, R.O.C.

and Pick place Service).

20004697

SIGURD MICROELECTRONICS CORPORATION The production testing of integrated circuits in

No. 436 SEC. 1

PEI-SHING RD., CHU-TUNG

HSIN-CHU TAIWAN, R.O.C. wafer and package form.

The manufacture of trimmed integrated circuits.

50600400

3F & 4F, No. 65, Guangfu N. Rd.

HSINCHU INDUSTRIAL PARK, HUKOU

HSIN-CHU TAIWAN, R.O.C.

SIGURD MICROELECTRONICS CORPORATION The production testing of integrated circuits in

wafer and package form.

The manufacture of trimmed integrated circuits.